



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10A105KO8NNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 1 µF, 16V, ±10%, X5R, 0603

## A. Samsung Part Number

<u>CL</u> <u>10</u> <u>A</u> <u>105</u> <u>K</u> <u>O</u> <u>8</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ 8 ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor									
2	Size	0603	(inch c	ode)	L:	1.6	± 0.1	mm	W:	0.8 ± 0.1	mm
3	Dielectric	X5R				8	Inner e	electrode	N	<b>J</b> i	
4	Capacitance	1	μF				Termin	ation	C	Cu	
(5)	Capacitance	±10	%				Plating	I	S	Sn 100%	(Pb Free)
	tolerance					9	Produc	et	N	lormal	
6	Rated Voltage	16	V			10	Specia	I	F	Reserved for	future use
7	Thickness	0.8	± 0.1	mm		11)	Packag	ging	C	Cardboard T	ype, 7" reel

## **B. Samsung Reliability Test and Judgement condition**

	Performance	Test condition						
Capacitance	Within specified tolerance	1kHz±10% 1.0±0.2Vrms						
Tan δ (DF)	0.05 max.							
Insulation	10,000Mohm or 100Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance	No abnormal exterior appearance	Microscope (×10)						
Withstanding	No dielectric breakdown or	250% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	X5R							
characteristics	(From -55℃ to 85℃, Capacitance change should be within ±15%)							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change: within ±12.5%	Bending to the limit (1mm)						
		with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120 ℃ for 10~30sec.)						
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5°C, 10±1sec.						
Soldering heat	Tan δ, IR : initial spec.	, , , , , , , , , , , , , , , , , , , ,						

	Performance	Test condition
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)
		2hours × 3 direction (x, y, z)
Moisture	Capacitance change: within ±12.5%	With rated voltage
Resistance	Tan δ : 0.075 max	40±2°C, 90~95%RH, 500+12/-0hrs
	IR: 500Mohm or 25Mohm · μF	
	Whichever is Smaller	
High Temperature	Capacitance change : within ±12.5%	With 200% of the rated voltage
Resistance	Tan δ : 0.075 max	Max. operating temperature
	IR: 1000Mohm or 50Mohm $\cdot \mu$ F	
	Whichever is Smaller	1000+48/-0hrs
Temperature	Capacitance change : within ±7.5%	1 cycle condition
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C
		→ Max. operating temperature → 25°C
		5 cycle test

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C , 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.